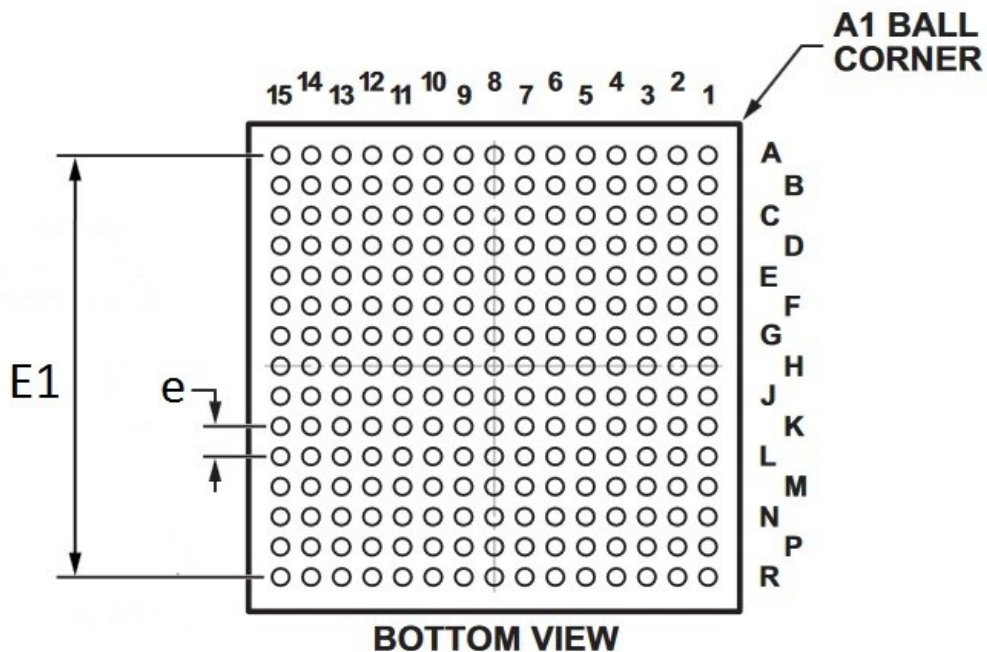


MBGA-225 1.0mm - stencil

Units		MILLIMETERS		
Dimension Limit		MIN	NOM	MAX
Contact Pitch	e	1.00		
Contact Pad Spacing	E1		14.00	
Contact Pad diameter	A1		0.55	

SMD Footprint



Stencil dimensions: 38mm x 28mm

Thickness: 100-127 μ m

Material: stainless steel or nickel silver

Manufacturing processes: lasering or chemical etching

Datasheet rev.: 1.04